

DATA SHEET

TEA6200

**Integrated AM upconversion
receiver**

Product specification
File under Integrated Circuits, IC01

August 1989

Integrated AM upconversion receiver**TEA6200****GENERAL DESCRIPTION**

The TEA6200 is an integrated AM upconversion receiver circuit with an IF of 10.7 MHz. Because of the high dynamic range of the RF prestage there is no tuned prestage. The whole selectivity is provided by crystal filters. The circuit is intended for use in AM radios with synthesizer tuning. The TEA6200 can handle RF signals up to 2 V RMS.

Features

- No pre-tuned selection is required
- No LW/MW switching
- RF input is protected from static discharge from the aerial
- Electronic standby switch
- Voltage controlled oscillator for synthesizer tuning
- IF output providing level information for search tuning.
- No alignment required.

QUICK REFERENCE DATA

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply voltage range	V_P	7.6	8.5	9.4	V
Supply current range	I_P	–	50	70	mA
AF output voltage with: RF at 1 MHz and 10 mV f_m at 400 Hz and 30%	V_{af}	–	350	–	mV
AGC start	V_{rf}	30	50	80	μ V
AGC range	ΔV_{rf}	–	95	–	dB

PACKAGE OUTLINE

20-lead dual in line; plastic (SOT146); SOT146-1; 1996 August 02.

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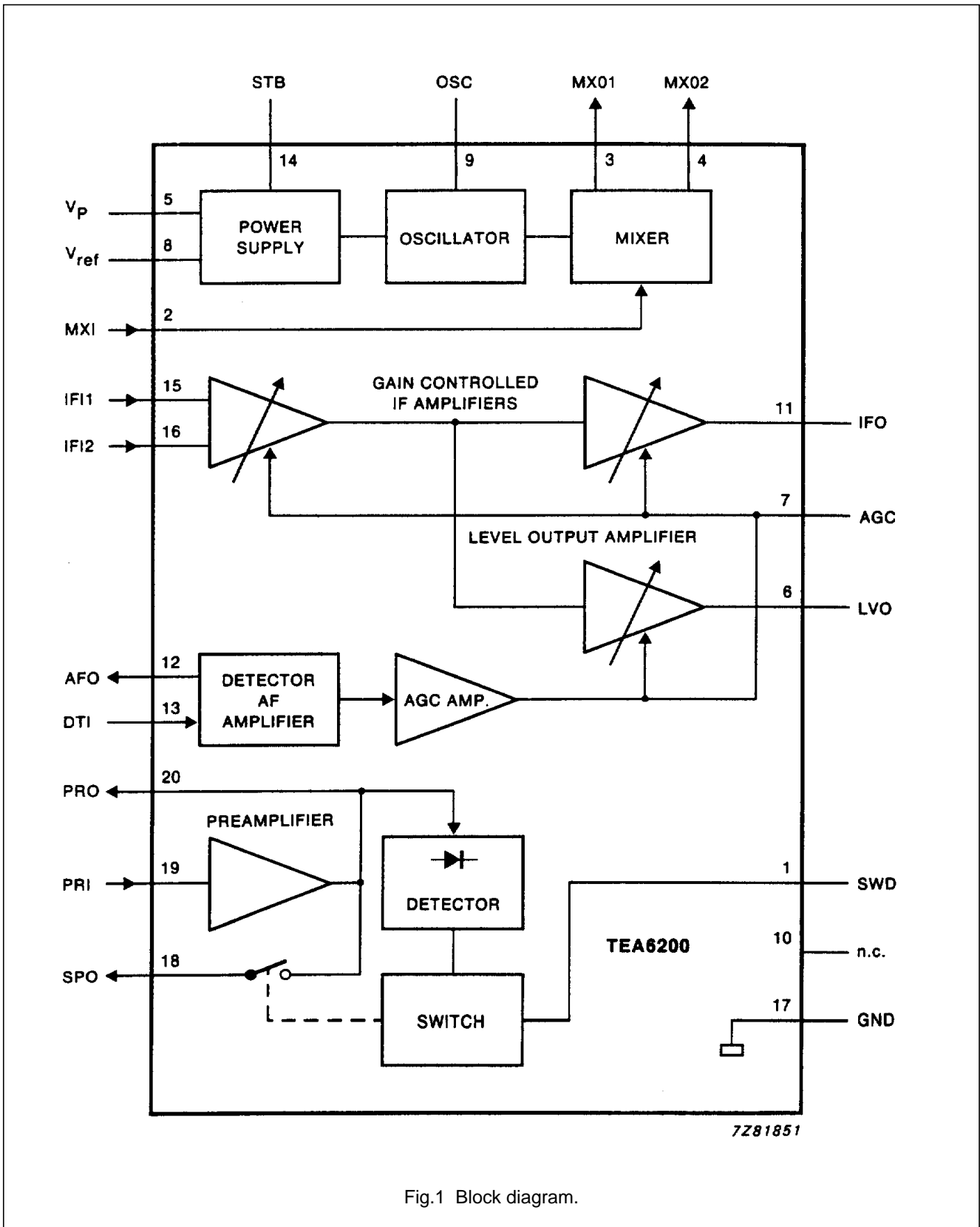


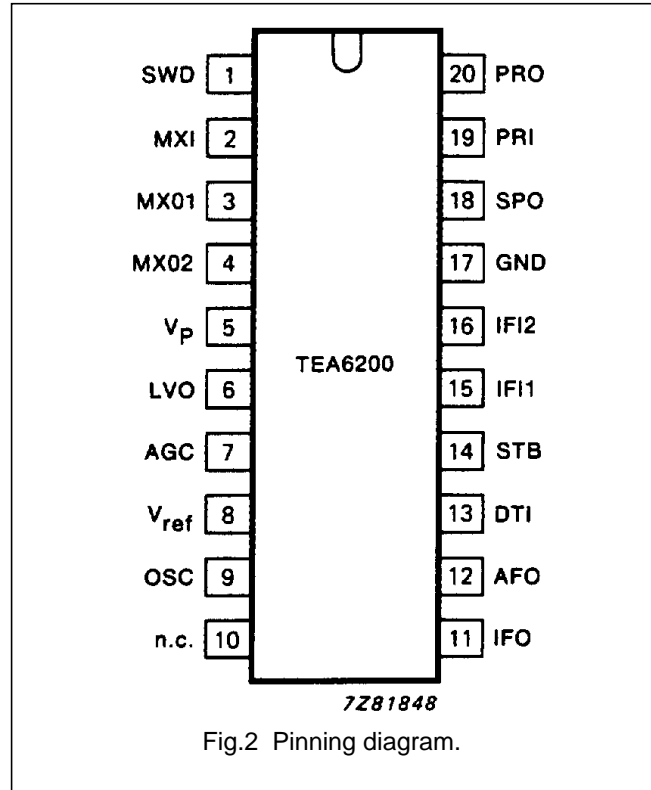
Fig.1 Block diagram.

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PINNING

1	SWD	switching delay
2	MXI	mixer input
3	MXO1	mixer output 1
4	MXO2	mixer output 2
5	V _P	supply voltage
6	LVO	level output
7	AGC	AGC time constant
8	V _{ref}	reference voltage
9	OSC	oscillator
10	n.c.	not internally connected*
11	IFO	IF output
12	AFO	AF output
13	DTI	detector input
14	STB	standby switch
15	IFI1	IF input 1
16	IFI2	IF input 2
17	GND	ground
18	SPO	switched prestage output
19	PRI	prestige input
20	PRO	prestige output



* Pin 10 must be connected to pin 5, 8 or 17.

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RATINGS

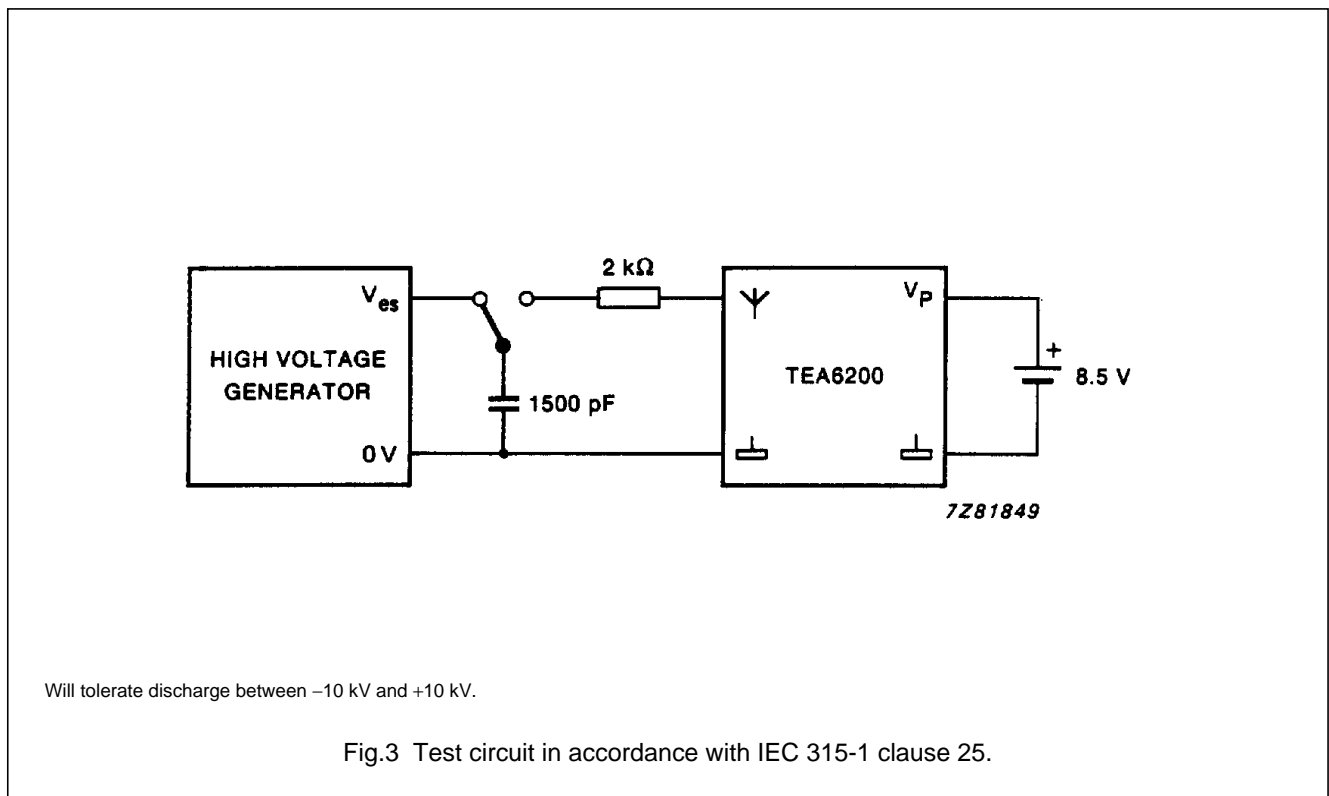
Limiting values in accordance with the Absolute Maximum System (IEC 134)

PARAMETER	SYMBOL	MIN.	MAX.	UNIT
Supply voltage	V_P	–	12	V
Supply current	I_P	–	70	mA
Total power dissipation	P_{tot}	–	850	mW
Operating ambient temperature range	T_{amb}	–30	+ 85	°C
Storage temperature range	T_{stg}	–40	+ 150	°C
Electrostatic discharge voltage	$\pm V_{es}$	–	10	kV

THERMAL RESISTANCE

From junction to ambient

$$R_{th\ j-a} = 80\ K/W$$



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DC CHARACTERISTICS

$V_P = 8.5\text{ V}$; $V_{14} = V_P$; Signal in OFF condition; all voltages referenced to ground unless otherwise specified.

PARAMETER	CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Mixer input		V_I	–	4.0	–	V
Mixer output 1		V_O	–	8.5	–	V
Mixer output 2		V_O	–	8.5	–	V
Level output		V_O	–	8.5	–	V
AGC voltage		V_{AGC}	–	0.65	–	V
Reference voltage		V_{ref}	–	4.0	–	V
Oscillator DC voltage		V_{OSC}	–	4.0	–	V
Prestage input		V_I	–	1.2	–	V
Prestage output		V_O	–	3.2	–	V

CHARACTERISTICS

$V_P = 8.5\text{ V}$; $T_{amb} = 25\text{ °C}$; $f_{RF} = 1\text{ MHz}$ at 10 mV RMS; $Q_{OSC} = 50$; modulation = 400 Hz at 30%; insertion loss of filters: crystal filter = 1 dB; ceramic filter = 4 dB, all voltages referenced to ground unless otherwise specified.

PARAMETER	CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply						
Supply voltage range		V_P	7.6	8.5	9.4	V
Supply current range		I_P	–	50	70	mA
Guaranteed operating voltage		V_P	7.0	–	10.0	V
Standby switch						
ON voltage		V_{14}	3.2	–	V_P	V
OFF voltage		V_{14}	0	–	1	V
ON current		$ I_{14} $	–	–	10	μA
OFF current		$-I_{14}$	–	–	0.5	mA
Supply current	device OFF note 1	I_P	–	–	10	mA
Prestage						
Switching threshold	modulation = 80%	V_{rf}	–	320	–	mV
Hysteresis		V_{rf}	1.5	3.5	5.5	dB
Oscillator						
Frequency range		f_{osc}	10.8	–	17.8	MHz
Oscillator amplitude		V_{osc}	200	420	–	mV
Tuned circuit selectivity		Q_{OSC}	20	50	–	–
Mixer						
Input capacitance		C_{2-8}	–	5	10	pF
Input impedance		Z_{2-8}	10	40	–	$k\Omega$
Conversion transconductance		I_{3-4}/V_{2-8}	–	3.8	–	S

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PARAMETER	CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT
IF amplifier						
Input impedance		R_{16-15}	10	–	–	$k\Omega$
Input capacitance		C_{16-15}	–	–	5	pF
Output impedance		Z_{11}	230	330	430	Ω
Detector						
	note 2					
Input impedance		Z_{13}	265	380	500	Ω
Output impedance		Z_{12}	7	10	14	$k\Omega$
Output level		V_{af}	250	350	500	mV
Reference voltage						
Voltage	$V_P = 8.5\text{ V}$	V_8	3.8	4.0	4.2	V
Output impedance		Z_8	–	20	–	Ω
Ripple rejection		$\frac{\Delta V_P}{\Delta V_8}$	40	–	–	dB
Level output pin 6						
	see Fig.5					
Output impedance		Z_6	–	1	–	$k\Omega$
Output voltage	$V_{rf} = 70\ \mu\text{V}$	V_6	0.5	0.7	1.0	mV
Output voltage	$V_{rf} = 2\text{ mV}$	V_6	–	15	–	mV
RF sensitivity						
RF input	$(S + N)/N = 6\text{ dB}$	V_{rf}	–	11	20	μV
	$(S + N)/N = 26\text{ dB}$	V_{rf}	–	110	150	μV
	$(S + N)/N = 46\text{ dB}$	V_{rf}	–	1100	2000	μV
	RF = 150 kHz					
	$(S + N)/N = 26\text{ dB}$	V_{rf}	–	200	–	μV
Output signal						
AF output voltage	$V_{rf} = 10\text{ mV}$	V_{af}	250	350	500	mV
	$V_{rf} = 20\ \mu\text{V}$	V_{af}	–	100	–	mV
Total distortion	$V_{rf} = 1\text{ mV};$ modulation = 80%	d_{tot}	–	3	5	%
Signal plus noise-to-noise ratio	RF = 10 mV to 1 V	$(S + N)/N$	53	57	–	dB
Ripple rejection	$V_P = 8.5\text{ V} + V_r$ 20 Hz < fR < 20 kHz $V_{rms} = 40\text{ mV}$	$\frac{\Delta V_P}{\Delta V_{af}}$	20	–	–	dB

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PARAMETER	CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Large signal handling						
Aerial input voltage	THD = 10%; modulation = 80%	V_{rf}	2	3	–	V
AGC range of preamplifier switch			–	12	–	dB
Switching threshold	modulation = 80%	V_{rf}	–	320	–	mV
Hysteresis	modulation = 80%	V_{rf}	1.5	3.5	5.5	dB
Ripple rejection of preamplifier	20 Hz < f_R < 1.5 MHz	$\frac{\Delta V_P}{\Delta V_{20}}$	–	40	–	dB
AGC						
AGC range			–	95	–	dB
Change of V_{af}	100 μ V < V_{rf} < 2 V		–	2	3	dB
AGC start		V_{rf}	30	50	80	μ V
Intermodulation free dynamic range						
Long wave second order	350/250 kHz input noise level = –99 dBm	I MFDR 2	72	82	–	dB
third order	input noise level = –99 dBm	I MFDR 3	–	86	–	dB
Medium wave second order	650/1550 kHz input noise level = –104 dBm	I MFDR 2	74	84	–	dB
third order	1.25/1.4 MHz input noise level = –104 dBm	I MFDR 3	–	90	–	dB

Notes to the characteristics

- The prestage is connected to the aerial by a 6 MHz low-pass filter that decouples unwanted aerial cable resonance frequencies. The large dynamic range of the prestage is achieved by use of a transimpedance amplifier with a feedback loop consisting of an equivalent aerial capacitance and a feedback capacitor. When large RF signals are received the feedback capacitance in the loop is increased and the gain subsequently reduced, (see Fig.4).

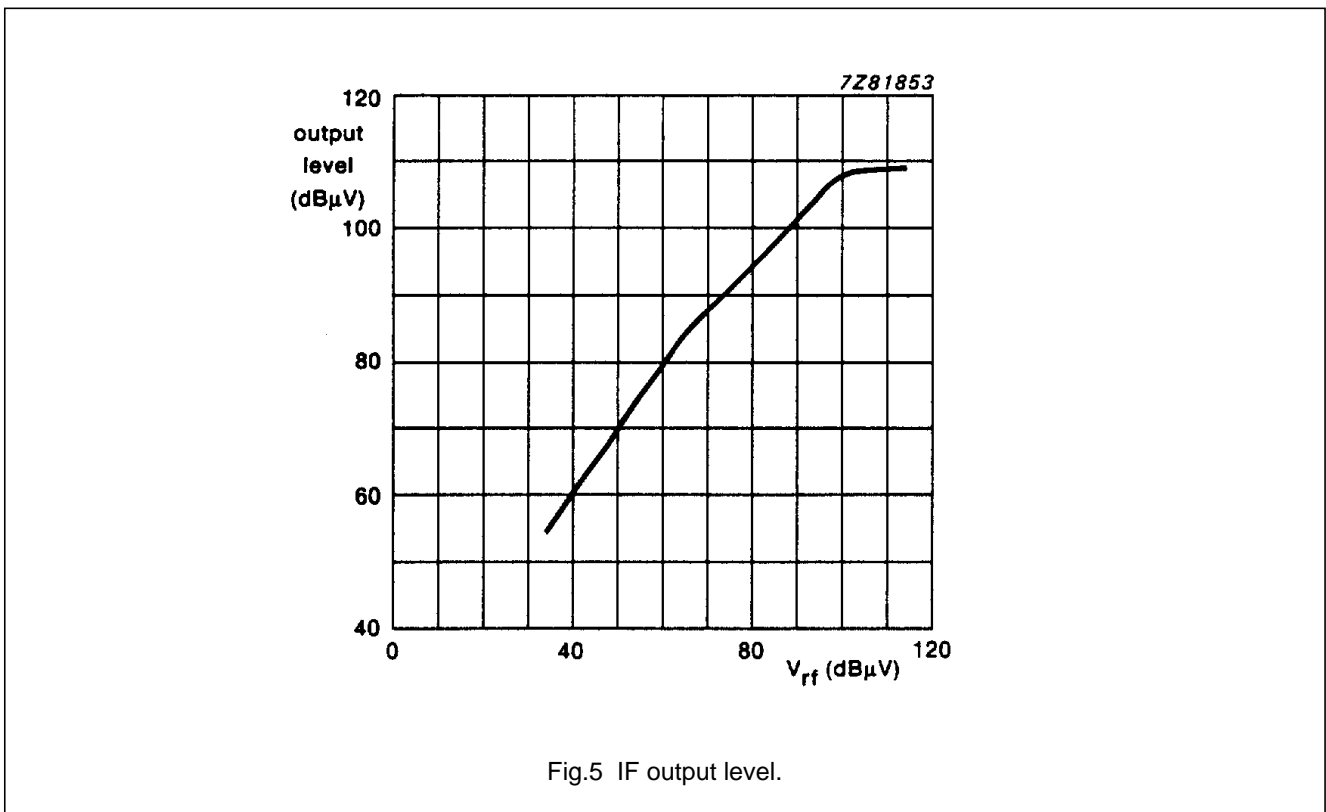
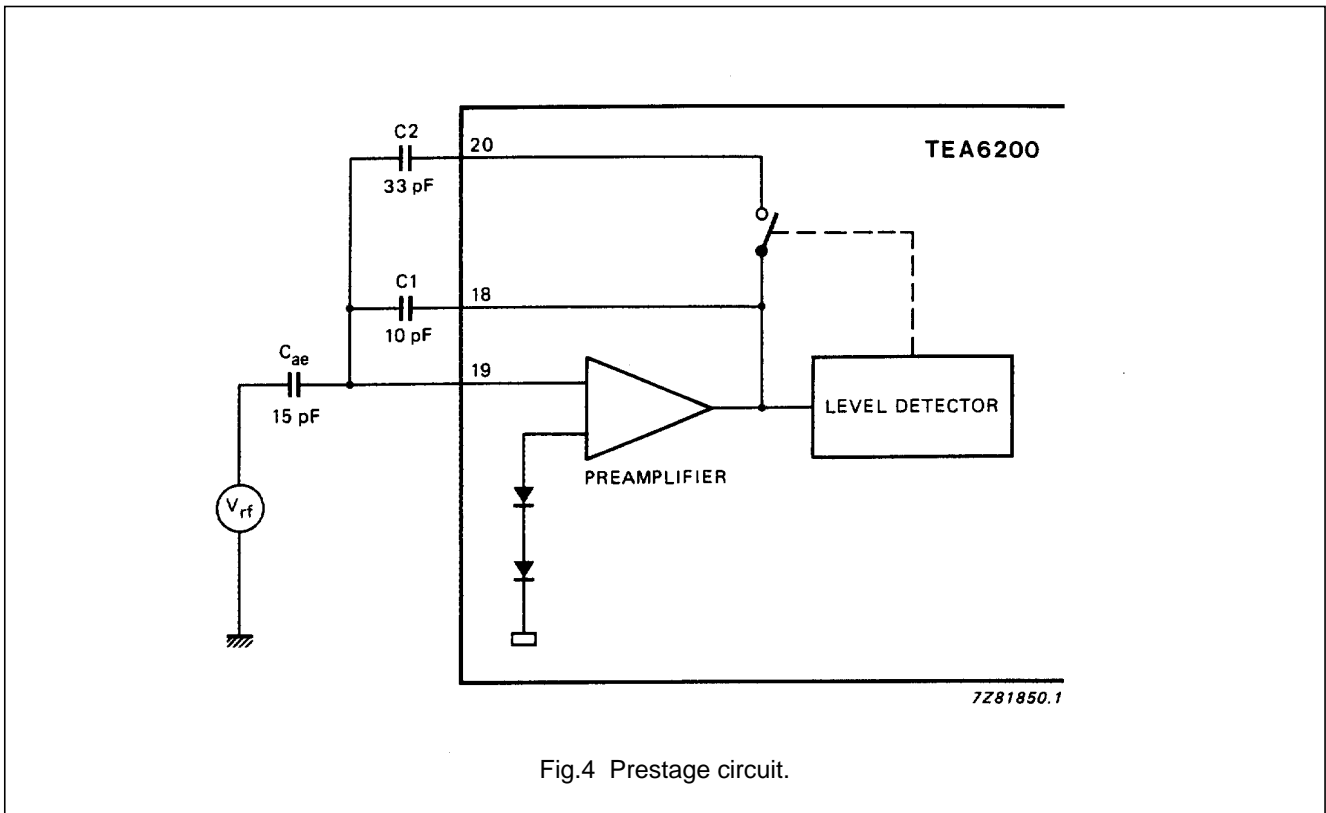
$$\text{Voltage gain for small signals} \quad G_V = V_{rf} \times \frac{C_{ae}}{C_1}$$

$$\text{Voltage gain for large signals} \quad G_V = V_{rf} \times \frac{C_{ae}}{C_1 + C_2}$$

- To protect the demodulator and the AGC circuitry, against parasitic oscillation in the IF section, a ceramic filter is connected between the IF output and detector input.

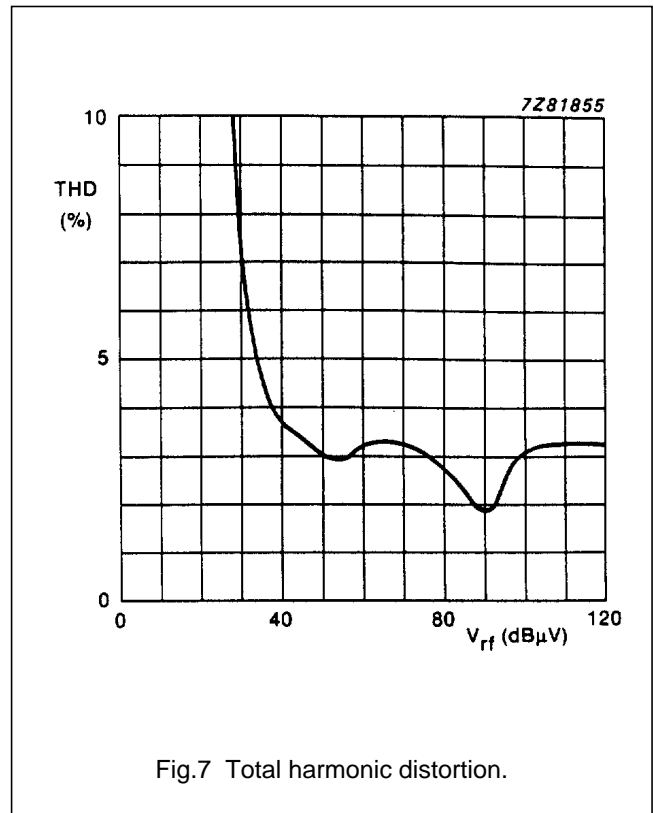
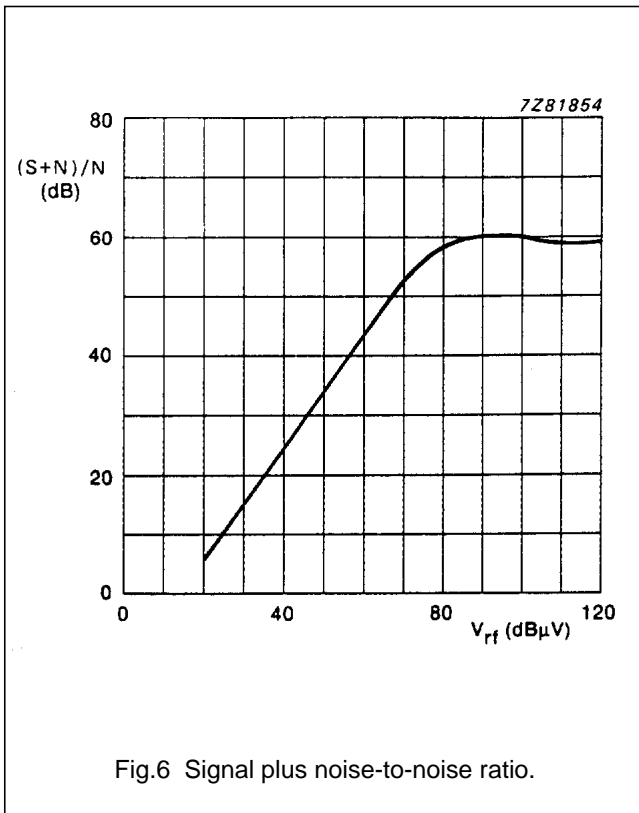
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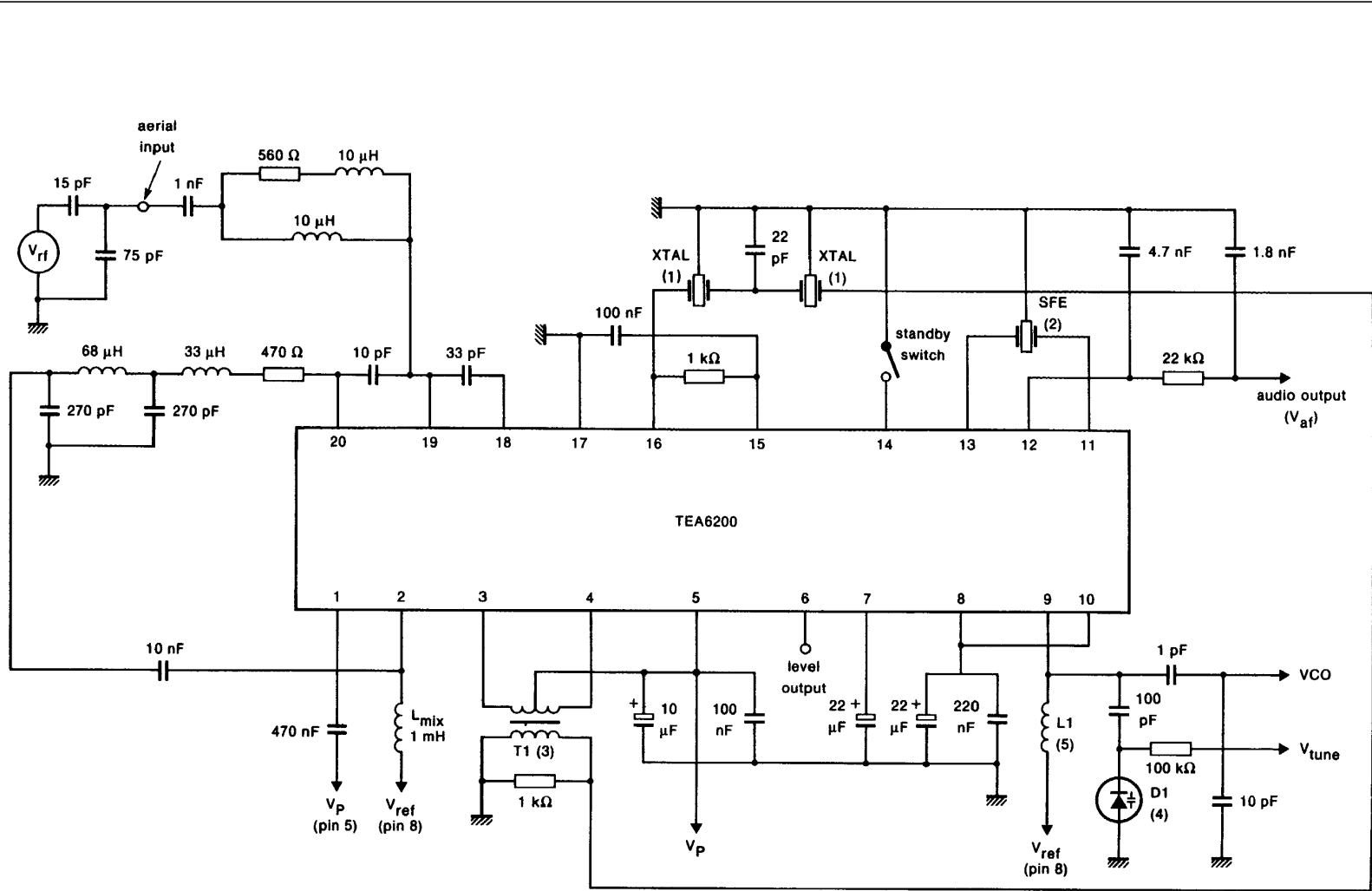
APPLICATION INFORMATION

Notes Fig. 8.

COMPONENT	CIRCUIT IDENTITY	SUPPLIER REFERENCE
(1) Crystal filters	XTAL	NDK 10T 7 BA
(2) Ceramic filter	SFE	Murata E 10 7 S
(3) Transformer	T1	Toko 7PS-1078 JK
(4) Variable capacitance diode.	D1	BB609, BB809 or BBY40
(5) Oscillator coil	L1	Toko 7PS-1077 X

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7Z81852.1

Fig.8 Application diagram.

APPLICATION INFORMATION

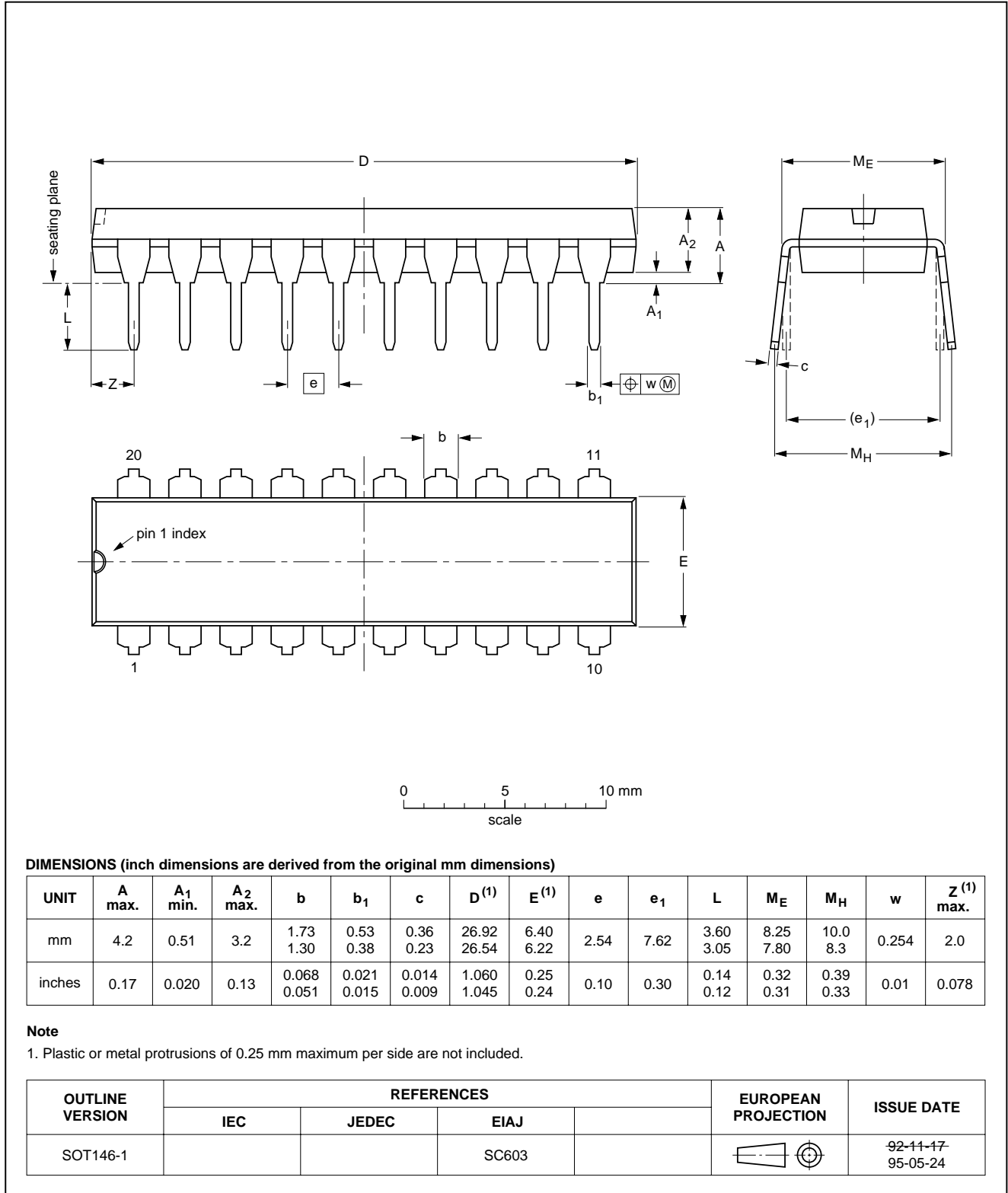
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PACKAGE OUTLINE

DIP20: plastic dual in-line package; 20 leads (300 mil)

SOT146-1



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SOLDERING

Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our "IC Package Databook" (order code 9398 652 90011).

Soldering by dipping or by wave

The maximum permissible temperature of the solder is 260 °C; solder at this temperature must not be in contact with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ($T_{stg\ max}$). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

Repairing soldered joints

Apply a low voltage soldering iron (less than 24 V) to the lead(s) of the package, below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than 300 °C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 °C, contact may be up to 5 seconds.

DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	

LIFE SUPPORT APPLICATIONS

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